

## **PSE Technology Corporation** SPECIFICATION FOR APPROVAL

CUSTOMER	
NOMINAL FREQUENCY	25.000000 MHz
HOLDER TYPE	TYPE FY 5.0x3.2 SEAM SEALED CRYSTAL
SPEC. NO. ( P/N )	FY2500016
CUSTOMER P/N	
ISSUE DATE	August 2, 2011
VERSION	C

APPROVED	PREPARED	QA
Alan Yang	Brenda	Canten
APPROVED BY CUSTOMER:		AVL Status
Please return one copy v	vith approval to PSE-TW	

## **PSE Technology Corporation**

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http://www.saronix-ecera.com.tw

\*Pb-free

\*RoHS Compliant

\*HF-Halogen Free

\*REACH Compliant



\*\*\* A company of PERICOM Semiconductor Corporation \*\*\*

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## **VERSION HISTORY**

Version No.	Version Date	Customer Receipt Date	Supplier Receipt Date	Description	Notes
А	Jul.16,2010			Initial Release	
В	May.12,2011			Updated Suggested IR Reflow Profile & Format	
С	Aug.2,2011			Added Maximum Drive Level: 500μW	

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### **ELECTRICAL SPECIFICATIONS**

Item	Symbol	Specifications	Units	Notes
Nominal Frequency	Fn	25.000000	MHz	
Mode of Oscillation	МО	AT Cut-Fundamental		
Calibration Load Capacitance	CL	18	pF	
Calibration Tolerance	FL	±30	ppm	at 25°C±3°C
Operating Temperature Range	TR	-20 to +70	°C	
Frequency Stability (Frequency Deviation over the Operating Temperature Range)	F/T	±30	ppm	Reference to the Frequency at 25°C
Operating Drive Level		300	μW	
Maximum Drive Level		500	μW	
Equivalent Series Resistance	ESR	30	Ω	Max
Shunt Capacitance	C0	5	pF	Max
Aging at 25°C		±3	ppm	Max, 1st year
Storage Temperature		-55 to +125	°C	
Insulation Resistance		500	МΩ	Min

\*\* This product doesn't include harmful substance that stipulated by SONY SS-00259 Level 1 and S-AT2-001 Level 1 standard. RoHS Compliant (Pb - Free).



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#### **RELIABILITY SPECIFICATIONS**

#### **MECHANICAL AND ENVIRONMENTAL RATINGS:**

a) FINE LEAK TEST: JESD22-A109 (Condition 1A)

b) GROSS LEAK TEST: JESD22-A109 (Condition C)

c) MOISTURE RESISTANCE: JESD22-A113

d) SHOCK: JESD22-B104 (Condition B)

e) SOLDERABILITY : (RoHS version): J-STD-002

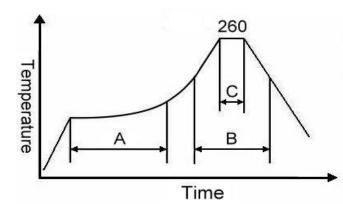
f) VIBRATION: JESD22-B103

g) SOLVENT RESISTANCE: JESD22-B107

h) RESISTANCE TO SOLDERING HEAT (RoHS version): J-STD-020D Table 5.2 Pb free devices (3 cycles max)

#### SUGGESTED IR REFLOW PROFILE

\*As per IPC-JEDEC J-STD-020D



#### Note:

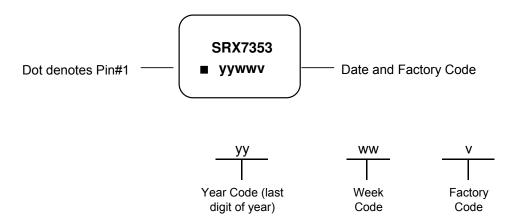
	Stage	Temperature	Time
Α	Preheat	150~200°C	60~120 Sec
В	Primary Heat	217°C	60~150 Sec
С	Peak	260°C	10 Sec

For soldering reflow profile and reliability test ratings go to: <a href="http://www.pericom.com/pdf/sre/reflow.pdf">http://www.pericom.com/pdf/sre/reflow.pdf</a>

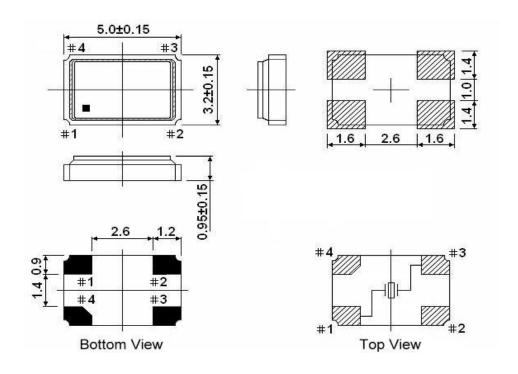
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#### **MARKING**



## MECHANICAL DRAWINGS (Scale: None. Dimensions are in mm.)



\*\* Recommended - Pin 1 & 3 : CRYSTAL Pin 2 & 4 : GND

#### Note:

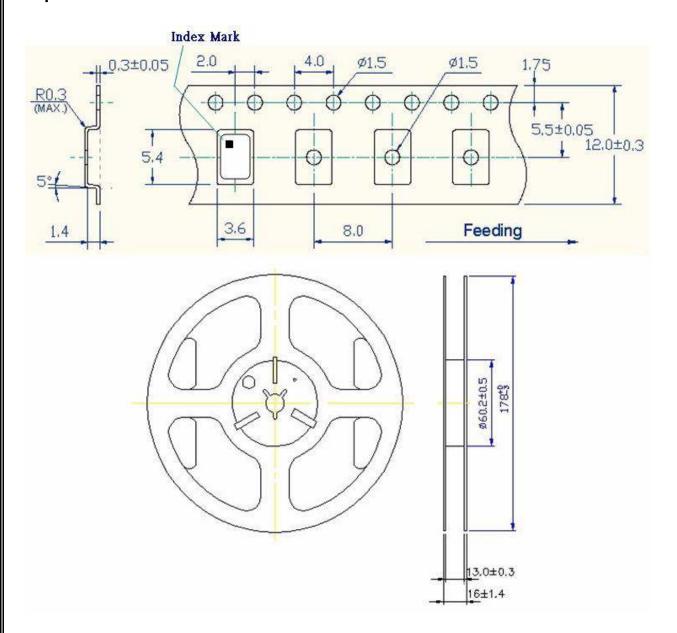
- 1. The marking dot denotes Pin#1.
- 2. Pin positions of the drawing is only for reference, and the Pin with chamfer is based on the real product.



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### Tape & Reel



- 1. 230mm minimum leafer which consist of carrier and/or tape followed by a minimum of 160mm of empty carrier tape sealed with cover tape.
- 2. 160mm minimum trailer of empty carrier tape sealed with cover tape.



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